

ABSTRACT

LEADED MCM PACKAGE AND METHOD THEREFOR

A method of packaging a leaded multi-chip package and a leaded multi-chip
5 package using a combination of substrate(1) and leadframe (7). A plurality of
integrated circuit (IC) chips (4,5) and possibly also passive components (6) are
attached onto a laminate substrate (1) which has printed conductive traces on one
side. Bonding wires (9, 10) are used to form interconnects between bond pads (15)
on the IC chips and bond fingers on the conductive traces (2,3) on the substrate (1)
10 and between a metallic leadframe (7) attached to the substrate (1) and further bond
fingers on the conductive traces (2,3) on the substrate (1). The substrate, IC chips,
bonding wires and internal portions of the metallic leadframe are encapsulated with
moulding compound (11). The external portions of the leadframe outside the
encapsulated area are formed into predetermined shapes such as gull-wing, straight or
15 J-shapes.

Figure 4